



## Specification for Approval

- DEVICE NUMBER: BL-BGE141K-3-CU-20F-L-AA-TBS25A
- CUSTOMER:



SAMPLES  
ATTACHED AREA

DATE \ PAGE	1	2	3	4	5	6	7	8			CONTENTS
2016/1/21	1.0	1.0	1.0	1.0	1.0	1.0					Original Released
2016/2/15	1.1	1.1	1.1	1.1	1.1	1.1	1.1	1.1			Modify dimensions
2022/8/3	1.2	1.2	1.2	1.2	1.2	1.2	1.2	1.2			Add IRON Soldering

### FOR CUSTOMER'S APPROVAL STAMP OR SIGNATURE

APPROVED	PURCHASE	MANUFACTURE	QUALITY	ENGINEERING

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Approved By	Confirmed By	Prepared By
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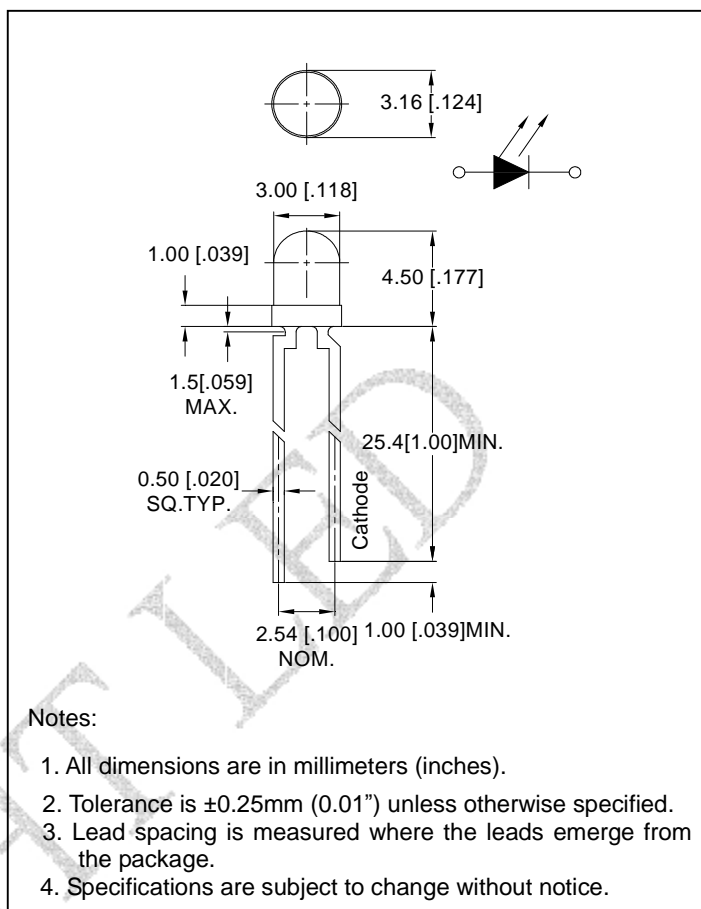
### ● Features:

1. Chip material: AlGaInP/GaAs
2. Emitted color : Green
3. Lens Appearance : Green Diffused
4. Low power consumption.
5. High efficiency.
6. Versatile mounting on P.C. Board or panel.
7. Low current requirement.
8. 3mm diameter package.
9. This product don't contained restriction Substance, compliance RoHS standard.

### ● Applications:

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

### ● Package dimensions



### ● Absolute maximum ratings(Ta=25°C)

Parameter	Symbol	Rating	Unit
Power Dissipation	Pd	70	mW
Forward Current	I <sub>F</sub>	30	mA
Peak Forward Current	I <sub>FP</sub>	150	mA
Reverse Voltage	V <sub>R</sub>	5	V
Operating Temperature	Topr	-40°C~100°C	
Storage Temperature	Tstg	-40°C~100°C	

\*1 Condition for I<sub>FP</sub> is pulse of 1/10 duty and 0.1msec width.

### ● Electrical and optical characteristics(Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	$V_F$	$I_F=2mA$	-	1.8	2.3	V
Luminous Intensity	$I_v$	$I_F=2mA$	-	7.0	-	mcd
Reverse Current	$I_R$	$V_R=5V$	-	-	100	$\mu A$
Peak Wave Length	$\lambda_p$	$I_F=2mA$	-	570	-	nm
Dominant Wave Length	$\lambda_d$	$I_F=2mA$	560	-	574	nm
Spectral Line Half-width	$\Delta \lambda$	$I_F=2mA$	-	30	-	nm
Viewing Angle	$2\theta_{1/2}$	$I_F=2mA$	-	85	-	deg

### ● Typical electro-optical characteristics curves

Fig.1 Relative intensity vs. Wavelength

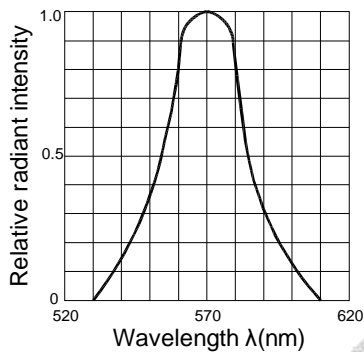


Fig.2 Forward current derating curve vs. Ambient temperature

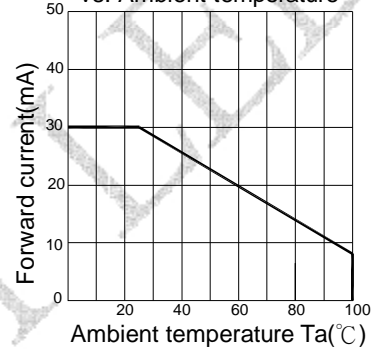


Fig.3 Forward current vs. Forward voltage

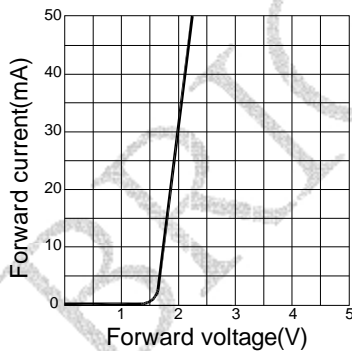


Fig.4 Relative luminous intensity vs. Ambient temperature

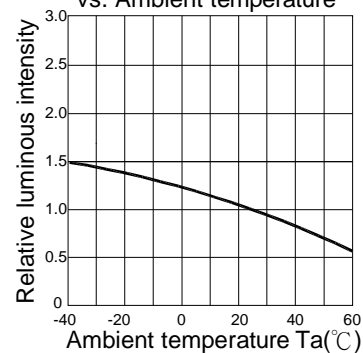


Fig.5 Relative luminous intensity vs. Forward current

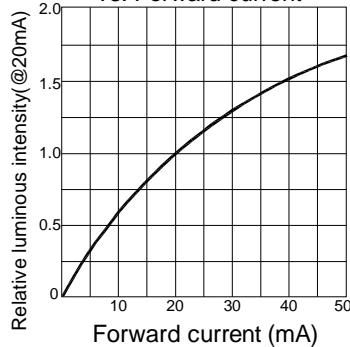
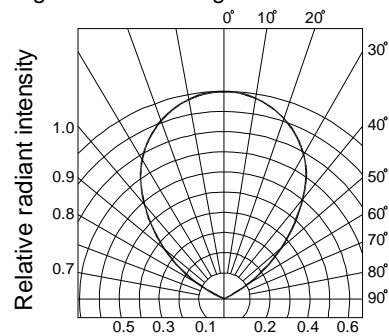


Fig.6 Radiation diagram





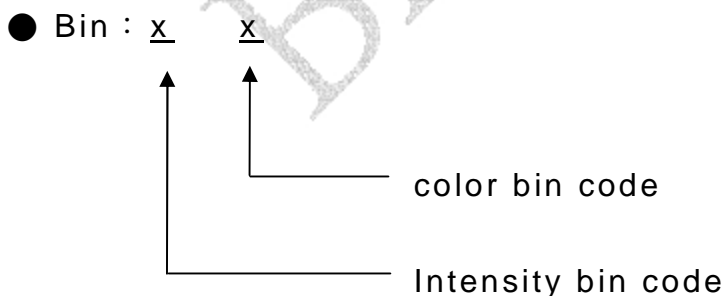
### ● Bin Limits

#### 1. Intensity Bin Limits (At $I_F=2\text{mA}$ )

Bin Code	Min. (mcd)	Max. (mcd)
F	2.4	3.7
G	3.7	5.5
H	5.5	8.2
J	8.2	12.3
K	12.3	18.5

#### 2. Color Bin Limits (At $I_F=2\text{mA}$ ) : Dominant Wave Length $\lambda_d(\text{nm})$

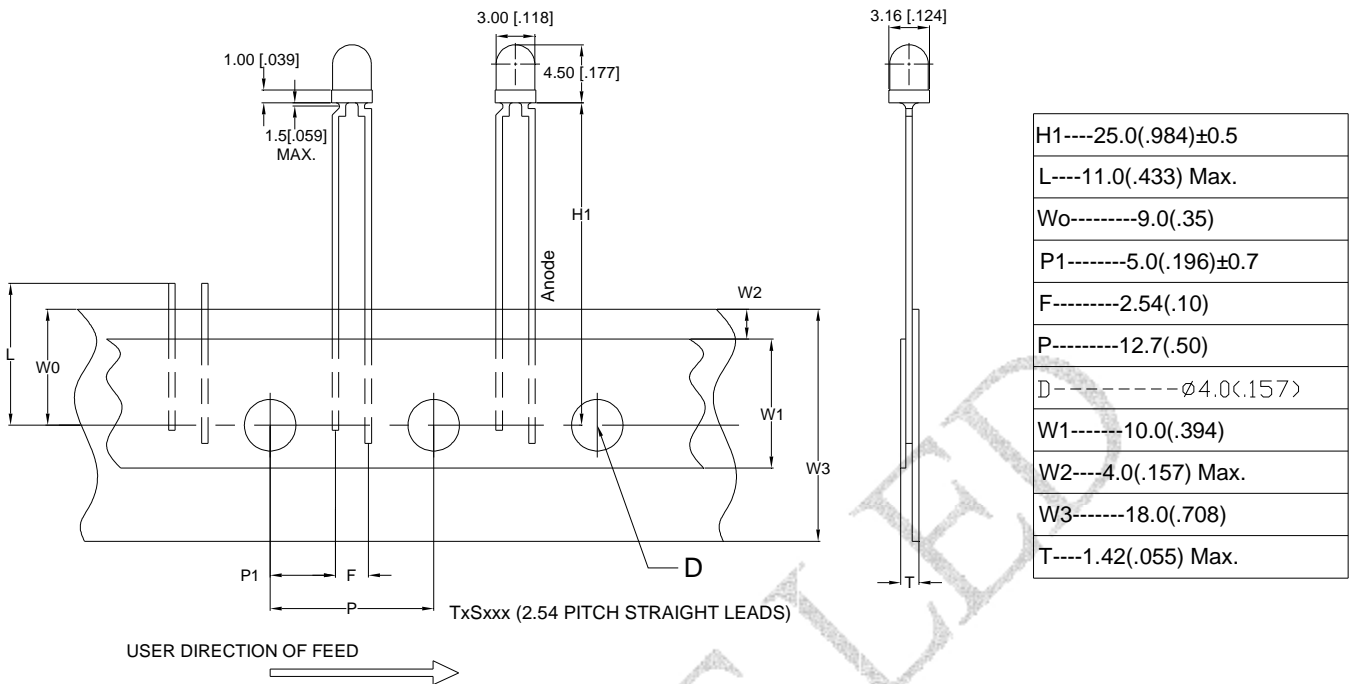
Bin Code	Min. (nm)	Max. (nm)
1	560	562
2	562	564
3	564	566
4	566	568
5	568	570
6	570	572
7	572	574



NOTES: 1. Tolerance of measurement of luminous intensity.  $\pm 15\%$

2. Tolerance of measurement of dominant wavelength  $\pm 1.0\text{nm}$

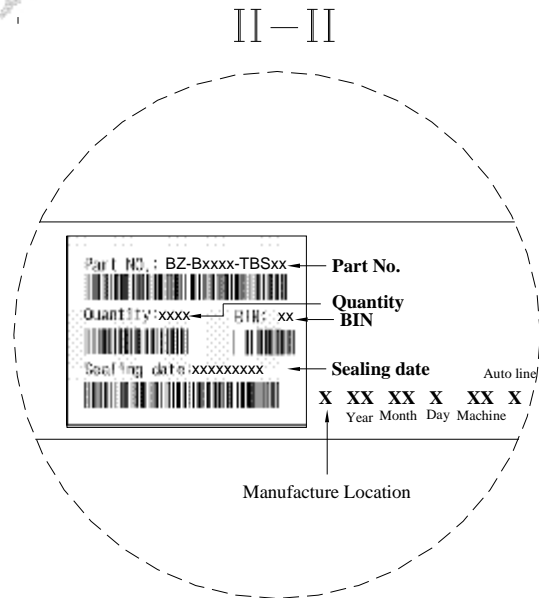
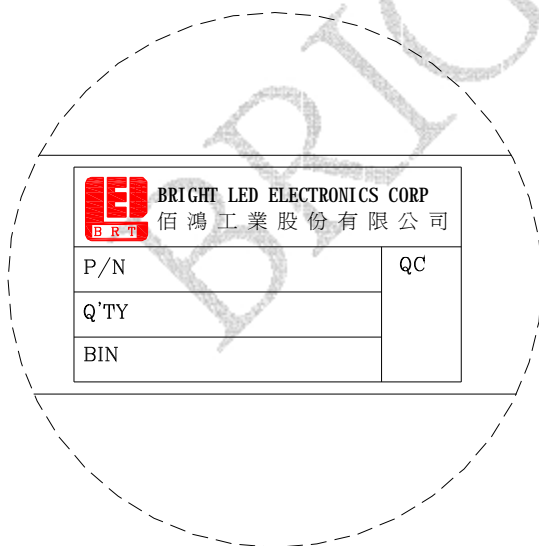
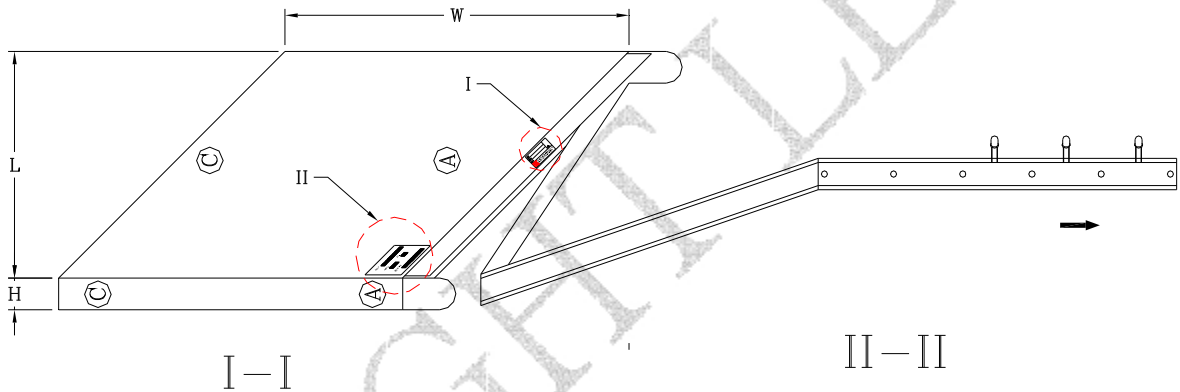
● Tapping and packaging specifications(Units: mm)



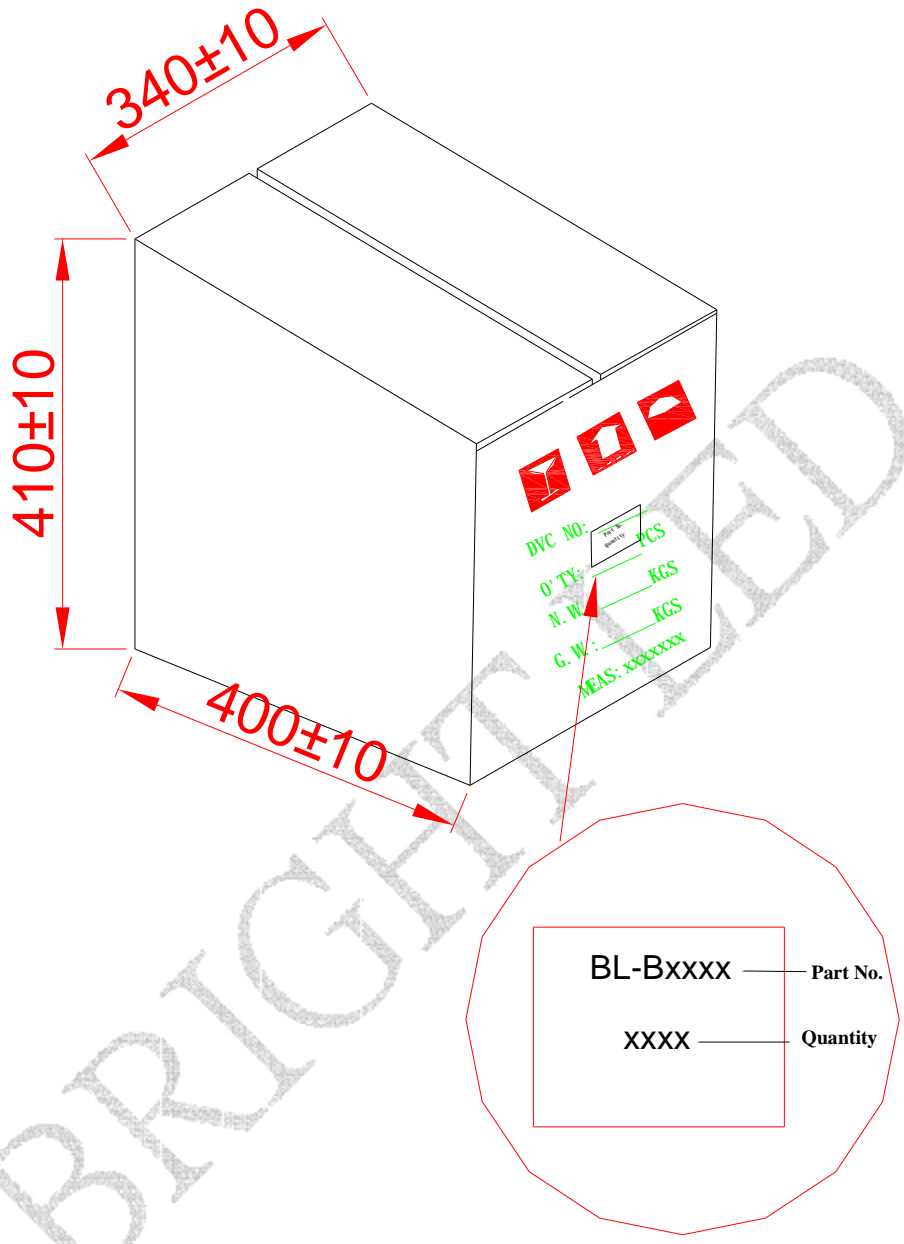
- Notes:
1. All dimensions are in millimeter (inch).
  2. Tolerance is  $\pm 0.25\text{mm}$  (0.01") unless otherwise specified.
  3. Lead spacing is measured where the leads emerge from the package.
  4. The stopper is used as the tie bar.

### ● PACKAGING DIMMENSIONS

ITEM	SYMBOL	SPECIFICATION			
		Minimum		Maximum	
		mm	inch	mm	inch
Overall Length	L	325.00	12.80	340.00	13.40
Overall Width	W	245.00	9.65	276.00	10.87
Overall Thickness	H	50.00	1.97	60.00	2.36



● PACKAGING CARTON DIMENSIONS



NOTES:

1. 4K PCS PER BOX, 40K PCS PER CARTON
2. ALL Dimensions are in millimeters (inches).
3. Specifications are subject to change without notice.



# BRIGHT LED ELECTRONICS CORP.

BL-BGE141K-3-CU-20F-L-AA-TBS25A

## ● Reliability Test

Classification	Test Item	Reference Standard	Test Conditions	Result
Endurance Test	Operation Life	MIL-STD-750:1026 MIL-STD-883:1005 JIS-C-7021 :B-1	$I_F=2mA$ $T_a=+25^{\circ}C \pm 5^{\circ}C$ Test time=1,000hrs	0/32
	High Temperature High Humidity Storage	MIL-STD-202:103B JIS-C-7021 :B-11	$T_a=+85^{\circ}C \pm 5^{\circ}C$ RH=90%-95% Test time=240hrs	0/32
	High Temperature Storage	MIL-STD-883:1008 JIS-C-7021 :B-10	High $T_a=+85^{\circ}C \pm 5^{\circ}C$ Test time=1,000hrs	0/32
	Low Temperature Storage	JIS-C-7021 :B-12	Low $T_a=-45^{\circ}C \pm 5^{\circ}C$ Test time=1,000hrs	0/32
Environmental Test	Temperature Cycling	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1010 JIS-C-7021 :A-4	$T_a: +85^{\circ}C (30min) \sim +25^{\circ}C (5min) \sim -45^{\circ}C (30min) \sim +25^{\circ}C (5min)$ Test Time : 70min/ctcle 10cycle	0/32
	Thermal Shock	MIL-STD-202:107D MIL-STD-750:1051 MIL-STD-883:1011	$-45^{\circ}C \pm 5^{\circ}C \sim +85^{\circ}C \pm 5^{\circ}C$ 20min 20min Test Time=10cycle	0/32
	Solder Resistance	MIL-STD-202:201A MIL-STD-750:2031 JIS-C-7021 :A-1	Preheating : 120°C, within 120-180 sec. Operation heating : 255°C±5°C within 5 sec. 260°C (Max)	0/32
	Solder ability	MIL-STD-202F:208D MIL-STD-750D:2026 MIL-STD-883D:2003 JIS C 7021:A-2	$T_{sol}=230 \pm 5^{\circ}C$ Dwell Time=5±1secs	0/32

## ● Judgment criteria of failure for the reliability

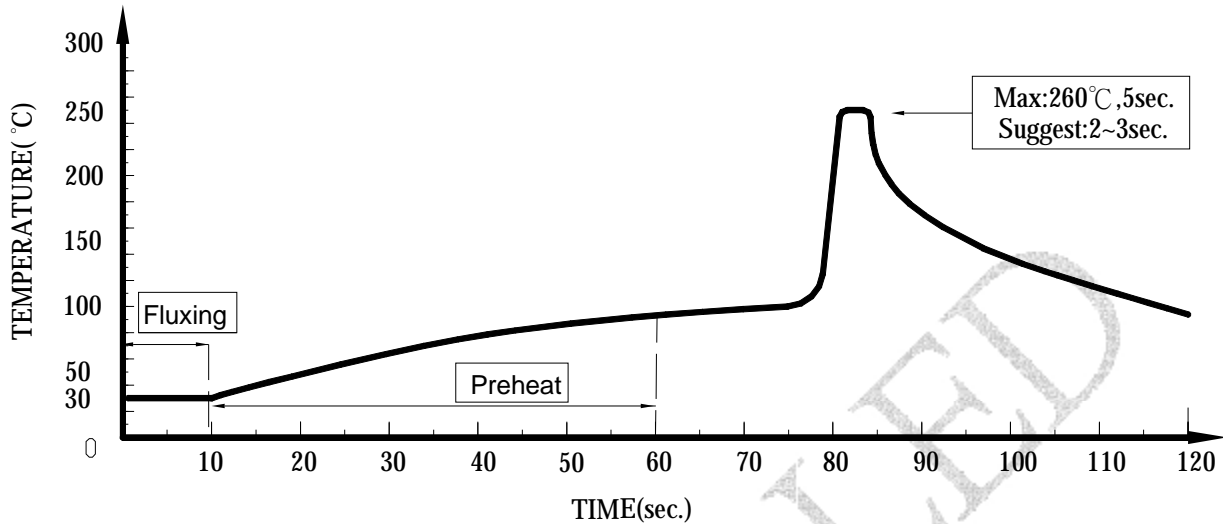
Measuring items	Symbol	Measuring conditions	Judgment criteria for failure
Forward voltage	$V_F (V)$	$I_F=2mA$	Over $U^1 \times 1.2$
Reverse current	$I_R (\mu A)$	$V_R=5V$	Over $U^1 \times 2$
Luminous intensity	$I_v (mcd)$	$I_F=2mA$	Below $S^1 \times 0.5$

Note: 1. U means the upper limit of specified characteristics. S means initial value.

2. Measurement shall be taken between 2 hours and after the test pieces have been returned to normal ambient conditions after completion of each test.



## ● Dip Soldering



1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
2. DIP soldering and hand soldering should not be done more than one time.
3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temperature.
4. Avoid rapid cooling during temperature ramp-down process
5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

## ● IRON Soldering

A : Max : 350°C Within 3 sec. One time only.

B : The products of 3mm without flange, welding condition of flat plate PCB Max : 350°C Within 2 sec. One time only

